INTEGRATED CIRCUITS

DATA SHEET

74LVC86Quad 2-input EXCLUSIVE-OR gate

Product specification Supersedes data of February 1996 IC24 Data Handbook







74LVC86

FEATURES

- Wide supply voltage range of 1.2 to 3.6 V
- In accordance with JEDEC standard no. 8-1A.
- Inputs accept voltages up to 5.5 V
- CMOS low power consumption
- Direct interface with TTL levels

DESCRIPTION

The 74LVC86 is a high-performance, low-power, low-voltage Si-gate CMOS device that is pin and superior to most advanced CMOS compatible TTL families.

Inputs can be driven from either 3.3 V or 5 V devices. This feature allows the use of these devices as translators in a mixed 3.3 V/5 V environment.

The 74LVC86 provides the 2-input EXCLUSIVE-OR function.

QUICK REFERENCE DATA

GND = 0 V; $T_{amb} = 25^{\circ}C$; $t_r = t_f \le 2.5 \text{ ns}$

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t _{PHL} t _{PLH}	Propagation delay nA, nB to nY	C _L = 15 pF; V _{CC} = 3.3 V	3.7	ns
C _I	Input capacitance		5.0	pF
C _{PD}	Power dissipation capacitance per gate	$V_{CC} = 3.3 \text{ V}, V_{I} = \text{GND to } V_{CC}^{1}$	55	pF

NOTE:

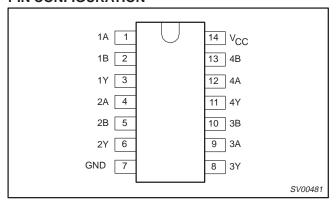
1. C_{PD} is used to determine the dynamic power dissipation (P_D in μW)

 $\begin{array}{l} P_D = C_{PD} \times V_{CC}^2 \times f_i + \Sigma \; (C_L \times V_{CC}^2 \times f_o) \; \text{where:} \\ f_i = \text{input frequency in MHz; } C_L = \text{output load capacity in pF;} \\ f_o = \text{output frequency in MHz; } V_{CC} = \text{supply voltage in V;} \end{array}$

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	PKG. DWG. #
14-Pin Plastic DIL	-40°C to +85°C	74LVC86 N	74LVC86 N	SOT27-1
14-Pin Plastic SO	−40°C to +85°C	74LVC86 D	74LVC86 D	SOT108-1
14-Pin Plastic SSOP Type II	−40°C to +85°C	74LVC86 DB	74LVC86 DB	SOT337-1
14-Pin Plastic TSSOP Type I	-40°C to +85°C	74LVC86 PW	74LVC86PW DH	SOT402-1

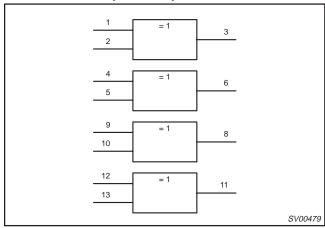
PIN CONFIGURATION



PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION
1, 4, 9, 12	1A – 4A	Data inputs
2, 5, 10, 13	1B – 4B	Data inputs
3, 6, 8, 11	1Y – 4Y	Data outputs
7	GND	Ground (0 V)
14	V _{CC}	Positive supply voltage

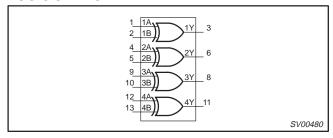
LOGIC SYMBOL (IEEE/IEC)



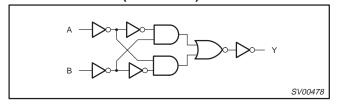
 $[\]Sigma (C_L \times V_{CC}^2 \times f_0) = \text{sum of the outputs.}$

74LVC86

LOGIC SYMBOL



LOGIC DIAGRAM (ONE GATE)



FUNCTION TABLE

INP	OUTPUTS	
nA	nY	
L	L	L
L	Н	Н
Н	L	Н
Н	Н	L

NOTES:

H = HIGH voltage level L = LOW voltage level

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	LIM	ITS	UNIT
STIMBUL	PARAMETER	CONDITIONS	MIN	MAX	UNIT
V _{CC}	DC supply voltage (for max. speed performance)		2.7	3.6	V
V _{CC}	DC supply voltage (for low-voltage applications)		1.2	3.6	V
VI	DC input voltage range		0	5.5	V
V _{I/O}	DC input voltage range for I/Os		0	V _{CC}	V
Vo	DC output voltage range		0	V _{CC}	V
T _{amb}	Operating free-air temperature range		-40	+85	°C
t _r , t _f	Input rise and fall times	$V_{CC} = 1.2 \text{ to } 2.7V$ $V_{CC} = 2.7 \text{ to } 3.6V$	0 0	20 10	ns/V

ABSOLUTE MAXIMUM RATINGS¹

In accordance with the Absolute Maximum Rating System (IEC 134). Voltages are referenced to GND (ground = 0V).

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +6.5	V
I _{IK}	DC input diode current	V _I < 0	-50	mA
VI	DC input voltage	Note 2	-0.5 to +5.5	V
V _{I/O}	DC input voltage range for I/Os		-0.5 to V _{CC} +0.5	V
I _{OK}	DC output diode current	$V_O > V_{CC}$ or $V_O < 0$	±50	mA
V _{OUT}	DC output voltage	Note 2	-0.5 to V _{CC} +0.5	V
I _{OUT}	DC output source or sink current	$V_O = 0$ to V_{CC}	±50	mA
I _{GND} , I _{CC}	DC V _{CC} or GND current		±100	mA
T _{stg}	Storage temperature range		-60 to +150	°C
P _{TOT}	Power dissipation per package – plastic mini-pack (SO) – plastic shrink mini-pack (SSOP and TSSOP)	above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	500 500	mW

NOTES

- Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the
 device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to
 absolute-maximum-rated conditions for extended periods may affect device reliability.
- 2. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions. Voltages are referenced to GND (ground = 0V).

				L	IMITS		
SYMBOL	PARAMETER	TEST CONDITIO	Temp = -	40°C to	°C to +85°C		
			MIN	TYP ¹	MAX		
V	HICH lovel Input voltage	V _{CC} = 1.2V		V _{CC}			V
V _{IH}	HIGH level Input voltage	V _{CC} = 2.7 to 3.6V		2.0]
	LOW level lengt voltage	V _{CC} = 1.2V				GND	V
V _{IL}	LOW level Input voltage	V _{CC} = 2.7 to 3.6V				0.8	
		$V_{CC} = 2.7V$; $V_I = V_{IH}$ or V_{IL} ; $I_O =$	= –12mA	V _{CC} - 0.5			
\ \ \	LUCI Llaval autaut valta aa	$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O =$	V _{CC} - 0.2	V _{CC}			
V _{OH}	HIGH level output voltage	$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O =$	V _{CC} -0.6			1 '	
		$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O =$	V _{CC} -1.0			1	
		$V_{CC} = 2.7V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = 0$	= 12mA			0.40	
V _{OL}	LOW level output voltage	$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; I_O	= 100μΑ		GND	0.20	V
		$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O =$	= 24mA			0.55	1
I _I	Input leakage current	$V_{CC} = 3.6V; V_I = 5.5V \text{ or GND}$	Not for I/O pins		±0.1	±5	μΑ
I _{IHZ} /I _{ILZ}	Input current for common I/O pins	$V_{CC} = 3.6V$; $V_I = V_{CC}$ or GND	•		±0.1	±15	μΑ
l _{OZ}	3-State output OFF-state current	$V_{CC} = 3.6V$; $V_I = V_{IH}$ or V_{IL} ; V_O	= V _{CC} or GND		0.1	±10	μΑ
I _{CC}	Quiescent supply current	V_{CC} = 3.6V; V_I = V_{CC} or GND; I	O = 0		0.1	20	μΑ
Δl _{CC}	Additional quiescent supply current per input pin	$V_{CC} = 2.7V \text{ to } 3.6V; V_I = V_{CC} - 0.000$	$V_{CC} = 2.7V$ to 3.6V; $V_I = V_{CC} - 0.6V$; $I_O = 0$			500	μА

NOTE:

AC CHARACTERISTICS

GND = 0 V; t_f = $t_f \leq$ 2.5 ns; C_L = 50 pF; R_L = 500 Ω ; T_{amb} = -40°C to +85°C

			LIMITS							
SYMBOL	SYMBOL PARAMETER		WAVEFORM $V_{CC} = 3.3V \pm 0.3V$.3V	٧	/ _{CC} = 2.7\	1	V _{CC} = 1.2V	UNIT
			MIN	TYP ¹	MAX	MIN	TYP ¹	MAX	TYP	
t _{PHL} / t _{PLH}	Propagation delay nA, nB to nY	Figures 1, 2	1.5	4.0	6.5	1.5	4.5	7.0	20	ns

NOTE:

AC WAVEFORMS

 $\rm V_M$ = 1.5 V at V_{CC} \geq 2.7 V; V_M = 0.5 at V_{CC} < 2.7 V; V_{OL} and V_OH are the typical output voltage drop that occur with the output load.

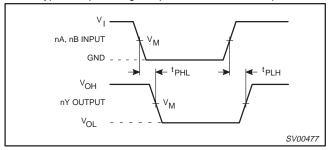


Figure 1. Input (nA, nB) to output (nY) propagation delays

TEST CIRCUIT

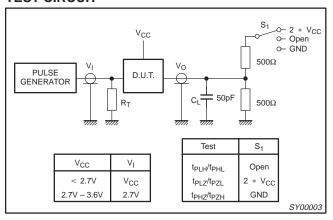


Figure 2. Load circuitry for switching times.

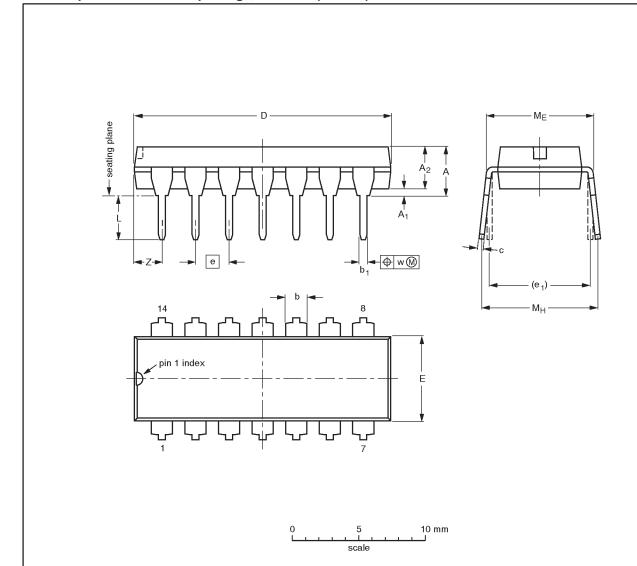
^{1.} All typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.

^{1.} These typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.

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DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	С	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

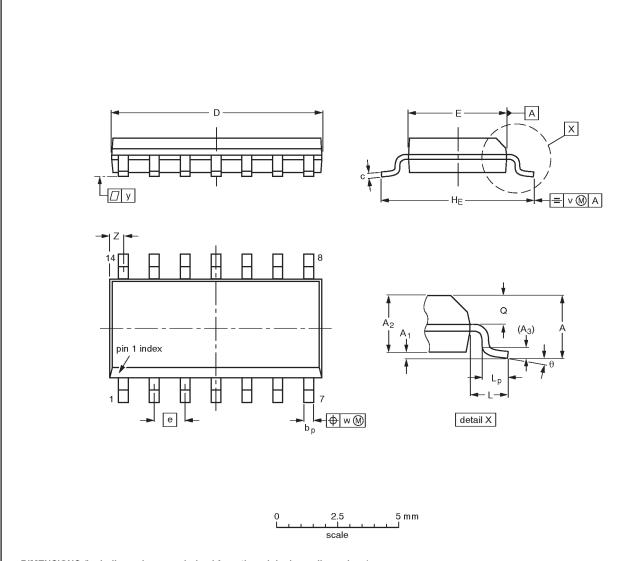
OUTLINE		REFER	RENCES		EUROPEAN	ISSUE DATE	
VERSION	IEC JEDEC EIAJ				PROJECTION	ISSUE DATE	
SOT27-1	050G04	MO-001AA				92-11-17 95-03-11	

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SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	Α1	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	1 // //60	0.0098 0.0039		0.01		0.0098 0.0075	0.35 0.34	0.16 0.15	0.050	0.24 0.23	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

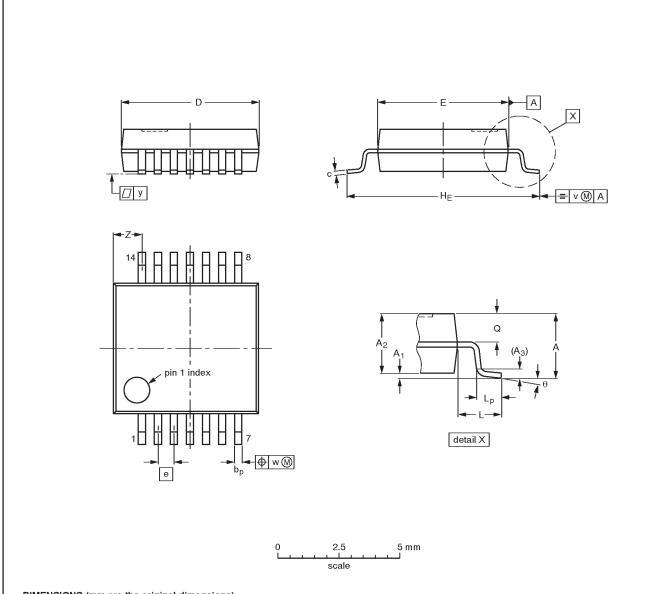
OUTLINE	OUTLINE		REFER	RENCES		EUROPEAN	ISSUE DATE	
	VERSION	IEC JEDEC EIAJ				PROJECTION	ISSUE DATE	
	SOT108-1	076E06\$	MS-012AB				91-08-13 95-01-23	

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SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	рb	c	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	٧	w	у	Z ⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.4 0.9	8° 0°

Note

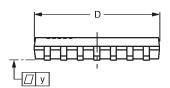
1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

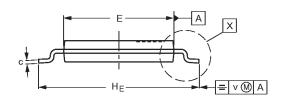
OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT337-1		MO-150AB				-95-02-04 96-01-18

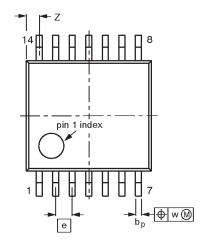
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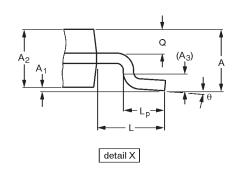
TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

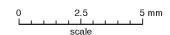
SOT402-1











DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A ₂	A ₃	bp	С	D ⁽¹⁾	E (2)	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE	ĺ
SOT402-1		MO-153			94-07-12 95-04-04	

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DEFINITIONS							
Data Sheet Identification	Product Status	Definition					
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.					
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